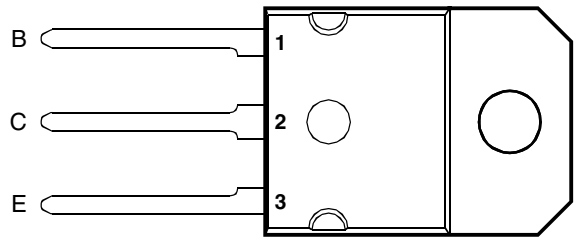




- Designed for Complementary Use with the BD746 Series
- 115 W at 25°C Case Temperature
- 20 A Continuous Collector Current
- 25 A Peak Collector Current
- Customer-Specified Selections Available

SOT-93 PACKAGE
(TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRAAA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

| RATING | | SYMBOL | VALUE | UNIT |
|--|--------|---------------------|-------------|------|
| Collector-base voltage ($I_E = 0$) | BD745 | V_{CBO} | 50 | V |
| | BD745A | | 70 | |
| | BD745B | | 90 | |
| | BD745C | | 110 | |
| Collector-emitter voltage ($I_B = 0$) | BD745 | V_{CEO} | 45 | V |
| | BD745A | | 60 | |
| | BD745B | | 80 | |
| | BD745C | | 100 | |
| Emitter-base voltage | | V_{EBO} | 5 | V |
| Continuous collector current | | I_C | 20 | A |
| Peak collector current (see Note 1) | | I_{CM} | 25 | A |
| Continuous base current | | I_B | 7 | A |
| Continuous device dissipation at (or below) 25°C case temperature (see Note 2) | | P_{tot} | 115 | W |
| Continuous device dissipation at (or below) 25°C free air temperature (see Note 3) | | P_{tot} | 3.5 | W |
| Unclamped inductive load energy (see Note 4) | | $\frac{1}{2}LI_C^2$ | 90 | mJ |
| Operating free air temperature range | | T_A | -65 to +150 | °C |
| Operating junction temperature range | | T_j | -65 to +150 | °C |
| Storage temperature range | | T_{stg} | -65 to +150 | °C |
| Lead temperature 3.2 mm from case for 10 seconds | | T_L | 260 | °C |

- NOTES: 1. This value applies for $t_p \leq 0.3$ ms, duty cycle $\leq 10\%$.
 2. Derate linearly to 150°C case temperature at the rate of 0.92 W/°C.
 3. Derate linearly to 150°C free air temperature at the rate of 28 mW/°C.
 4. This rating is based on the capability of the transistor to operate safely in a circuit of: $L = 20$ mH, $I_{B(on)} = 0.4$ A, $R_{BE} = 100 \Omega$, $V_{BE(off)} = 0$, $R_S = 0.1 \Omega$, $V_{CC} = 20$ V.

PRODUCT INFORMATION

electrical characteristics at 25°C case temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | | MIN | TYP | MAX | UNIT |
|--|---|--|--|-------------------------------------|-----------------------|--------------------------|------|
| $V_{(BR)CEO}$ Collector-emitter breakdown voltage | $I_C = 30 \text{ mA}$ | $I_B = 0$ | (see Note 5) | BD745 BD745A BD745B BD745C | 45 60 80 100 | | V |
| I_{CBO} Collector cut-off current | $V_{CE} = 50 \text{ V}$ $V_{CE} = 70 \text{ V}$ $V_{CE} = 90 \text{ V}$ $V_{CE} = 110 \text{ V}$ | $V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$ | $T_C = 125^\circ\text{C}$ $T_C = 125^\circ\text{C}$ $T_C = 125^\circ\text{C}$ $T_C = 125^\circ\text{C}$ | BD745 BD745A BD745B BD745C | | 0.1 0.1 0.1 0.1 | mA |
| I_{CEO} Collector cut-off current | $V_{CE} = 30 \text{ V}$ $V_{CE} = 60 \text{ V}$ | $I_B = 0$ $I_B = 0$ | | BD745/745A BD745B/745C | | 0.1 0.1 | mA |
| I_{EBO} Emitter cut-off current | $V_{EB} = 5 \text{ V}$ | $I_C = 0$ | | | | 0.5 | mA |
| h_{FE} Forward current transfer ratio | $V_{CE} = 4 \text{ V}$ $V_{CE} = 4 \text{ V}$ $V_{CE} = 4 \text{ V}$ | $I_C = 1 \text{ A}$ $I_C = 5 \text{ A}$ $I_C = 20 \text{ A}$ | (see Notes 5 and 6) | | 40 20 5 | 150 | |
| $V_{CE(sat)}$ Collector-emitter saturation voltage | $I_B = 0.5 \text{ A}$ $I_B = 5 \text{ A}$ | $I_C = 5 \text{ A}$ $I_C = 20 \text{ A}$ | (see Notes 5 and 6) | | | 1 3 | V |
| V_{BE} Base-emitter voltage | $V_{CE} = 4 \text{ V}$ $V_{CE} = 4 \text{ V}$ | $I_C = 5 \text{ A}$ $I_C = 20 \text{ A}$ | (see Notes 5 and 6) | | | 1 3 | V |
| h_{fe} Small signal forward current transfer ratio | $V_{CE} = 10 \text{ V}$ | $I_C = 1 \text{ A}$ | $f = 1 \text{ kHz}$ | | 25 | | |
| $ h_{fe} $ Small signal forward current transfer ratio | $V_{CE} = 10 \text{ V}$ | $I_C = 1 \text{ A}$ | $f = 1 \text{ MHz}$ | | 5 | | |

NOTES: 5. These parameters must be measured using pulse techniques, $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$.

6. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

thermal characteristics

| PARAMETER | MIN | TYP | MAX | UNIT |
|---|-----|-----|------|---------------------------|
| $R_{\theta JC}$ Junction to case thermal resistance | | | 1.1 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ Junction to free air thermal resistance | | | 35.7 | $^\circ\text{C}/\text{W}$ |

resistive-load-switching characteristics at 25°C case temperature

| PARAMETER | TEST CONDITIONS † | | | MIN | TYP | MAX | UNIT |
|--------------------|---|---|---|-----|-----|-----|------|
| t_d Delay time | $I_C = 5 \text{ A}$ $V_{BE(off)} = -4.2 \text{ V}$ | $I_{B(on)} = 0.5 \text{ A}$ $R_L = 6 \Omega$ | $I_{B(off)} = -0.5 \text{ A}$ $t_p = 20 \mu\text{s}$, $dc \leq 2\%$ | | 20 | | ns |
| t_r Rise time | | | | | 350 | | ns |
| t_s Storage time | | | | | 500 | | ns |
| t_f Fall time | | | | | 400 | | ns |

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

TYPICAL CHARACTERISTICS

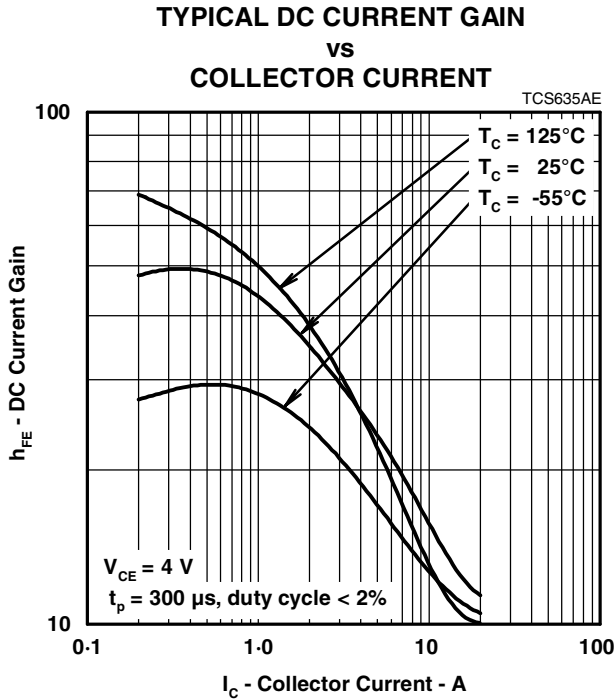


Figure 1.

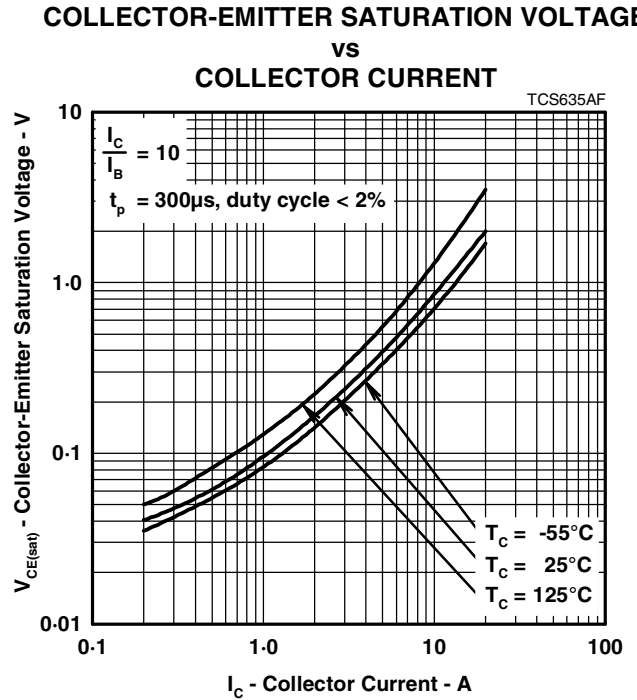


Figure 2.

MAXIMUM SAFE OPERATING REGIONS

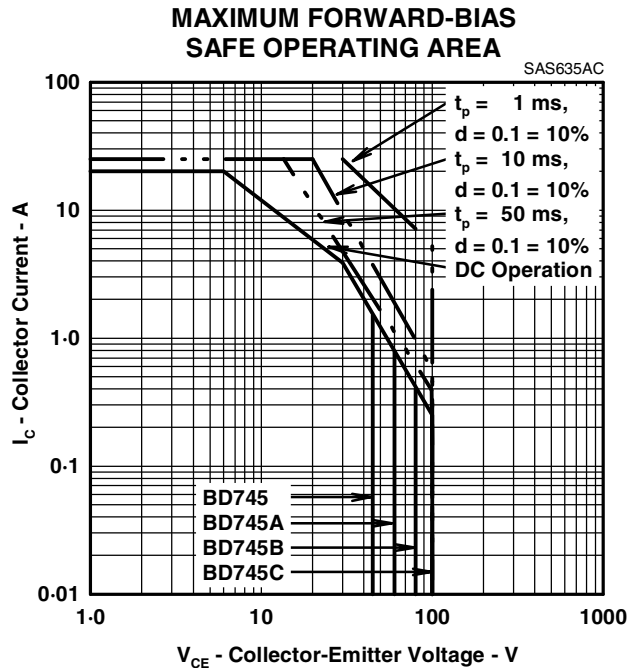


Figure 3.

PRODUCT INFORMATION

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THERMAL INFORMATION

**MAXIMUM POWER DISSIPATION
VS
CASE TEMPERATURE**

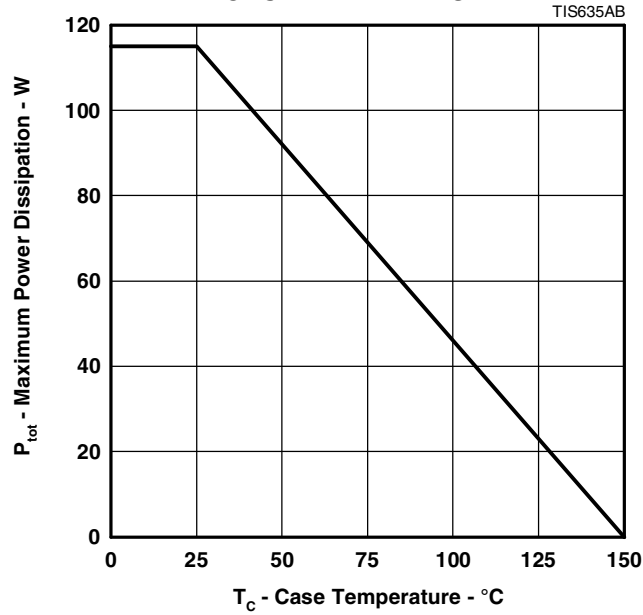


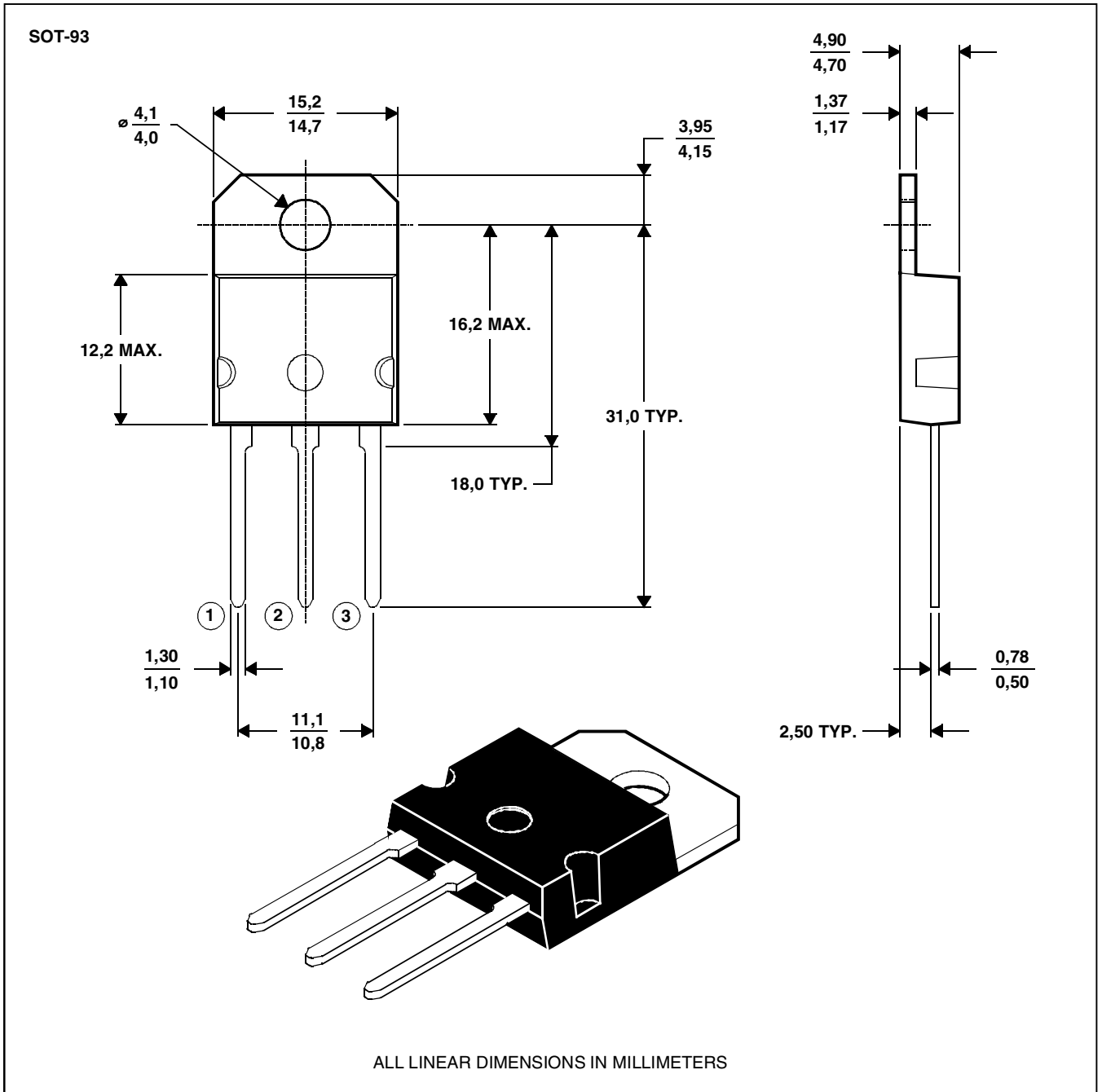
Figure 4.

MECHANICAL DATA

SOT-93

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

MDXXAW

PRODUCT INFORMATION

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